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**PCI Express 1.0mm Pitch Connector**

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**1. SCOPE****1.1. CONTENTS**

This specification covers the performance, tests and quality requirements for the PCI Express 1.0 pitch Connector.

**1.2. QUALIFICATION**

When tests are performed on the subject product line, the procedures specified in Tyco 109 series specifications shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

**2. APPLICABLE DOCUMENT**

The following Tyco documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

**2.1. TYCO SPECIFICATIONS**

- A. 109-1: General Requirements for Test Specifications
- B. 109-197 : Tyco Specification vs EIA and IEC Test Methods
- C. 501-57593 : Test Report

**3. REQUIREMENTS****3.1. DESIGN AND CONSTRUCTION**

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

**3.2. MATERIALS**

- A. Housing : Thermoplastic or Thermoplastic High Temp., UL94V-0
- B. Contact : Copper Alloy, Gold plating on contact area, Tin or Tin-Lead Plating on soldertail over Nickel underplating overall.

**3.3. RATINGS**

- A. Voltage: 250 VAC rms.
- B. Current: 1 A Max
- C. Temperature: - 40°C to 85 °C

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**3.4. PERFORMANCE REQUIREMENT AND TEST DESCRIPTION**

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. All tests shall be performed at ambient environmental conditions per AMP Specification 109-1 TEST REQUIREMENTS AND PROCEDURES SUMMARY.

**3.5. TEST REQUIREMENTS AND PROCEDURES SUMMARY**

Test Item		Requirement	Procedure
1	Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection.
<b>ELECTRICAL REQUIREMENT</b>			
2	Contact Resistance	30 m Ohm Max(Initial) 40 m Ohm Max(Final)	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max. EIA-364-6B. Refer to Fig.3
3	Dielectric withstanding Voltage	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX	400 VAC for 1minute Test between adjacent circuits of unmated connector. EIA-364-20B
4	Insulation Resistance	800 M Ohm Min.	Impressed voltage 500 VDC. Test between adjacent circuits of unmated connector. EIA-364-21C.
<b>MECHANICAL REQUIREMENT</b>			
6	Connector Mating Force	117 gf/ per pair Max.	Operation Speed : 25 mm/min. Measure the force required to mate connector. EIA-364-13B
7	Connector Unmating Force	15 gf/ per pair Min.	Operation Speed : 25 mm/min. Measure the force required to unmate connector. EIA-364-13B
8	Durability	See Note	Operation Speed : 500 cycles/hour. Durability Cycles : 100 Cycles EIA-364-9C
9	Contact Retention Force	0.5 kgf /per pair Min.	Measure the contact retention force with Tensile strength tester.
10	Solder ability	The inspected area of each lead must have 95% solder coverage minimum.	Steam Aging Preconditioning : 93+3/-5°C 、100%HR 、8hrs. <J-STD-002 category 3 aging> Solder pot temperature: 245±5°C, 5sec

Figure 1 ( Cont. )

ENVIRONMENTAL REQUIREMENTS		
TEST ITEM	REQUIREMENT	PROCEDURE
Resistance to Wave Soldering Heat [For customer drawing is applied with wave process, See note 2]	No physical damage shall occur. (Apply to product whose contacts with Tin-Lead plating)	Solder Temp. : 240±5°C, 10±0.5sec. Tyco spec. 109-202, Condition A
Resistance to Wave Soldering Heat [For customer drawing is applied with wave process, See note 2]	No physical damage shall occur. (Apply to product whose contacts with non-Lead plating and to Tyco Spec. 109-201, Condition B)	Solder Temp. : 265±5°C, 10±0.5sec. Tyco spec. 109-202, Condition B
11 Resistance to Reflow Soldering Heat [For customer drawing is applied with Reflow process, See note 2]	No physical damage shall occur. (Apply to product whose contacts with Tin-Lead plating)	Pre Heat : 100~150°C, 60 sec Max. Heat : 210°C Min., 30 sec Max. Peak Temp. : 240°C Max., 10±0.5sec.
Resistance to Reflow Soldering Heat [For customer drawing is applied with Reflow process, See note 2]	No physical damage shall occur. (Apply to product whose contacts with non-Lead plating)	Pre-soak condition, 85°C/85% RH for 168 hours. Pre Heat : 150~180°C, 90±30sec. Heat : 230°C Min., 30±10sec. Peak Temp. : 260+0/-5°C, 20~40sec. Duration : 3 cycles Tyco spec. 109-201, Condition B
12 Salt Spray	No detrimental corrosion allowed in contact area and base metal exposed.	Subject mated connectors to 35+/-2 °C and 5+/-1% salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B.

Figure 1 ( End )

Note 1 : Shall meet visual requirements, show no physical damage, and meet requirement of additional tests as specified in the test sequence in Figures 2

Note 2 : Resistance to soldering process is indicated on notes of customer drawing. Select the appropriate one which drawing notes content is matched with.

**3.6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST**

Test or Examination	Test Group				
	A	B	C	D	E
	Test Sequence (a)				
Examination of Product	1,4	1, 9	1, 5	1, 3,5	1, 3
Contact Resistance		2, 8	2,4		
Dielectric withstanding Voltage	3				
Insulation Resistance	2				
Mating Force		3, 7			
Unmating Force		4, 6			
Durability		5			
Contact Retention Force				4	
Solderability					2
Resistance to Soldering Heat				2	
Salt Spray			3		

**Figure 2**

**NOTE : (a) Numbers indicate sequence in which tests are performed**

**(b) Discontinuities shall not take place in this test group, during tests.**

**Figure 3. Contact Resistance & Resistance to flow solder heat**

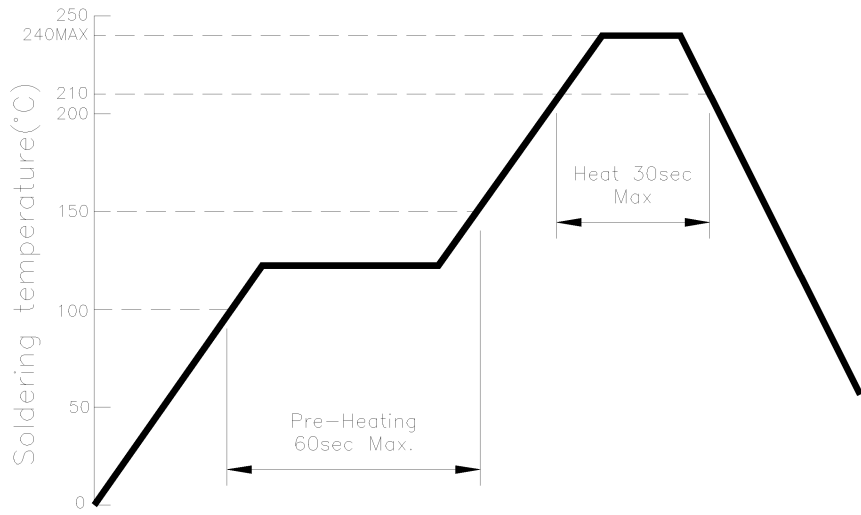


Fig.3-1 Temperature Profile of Reflow Soldering

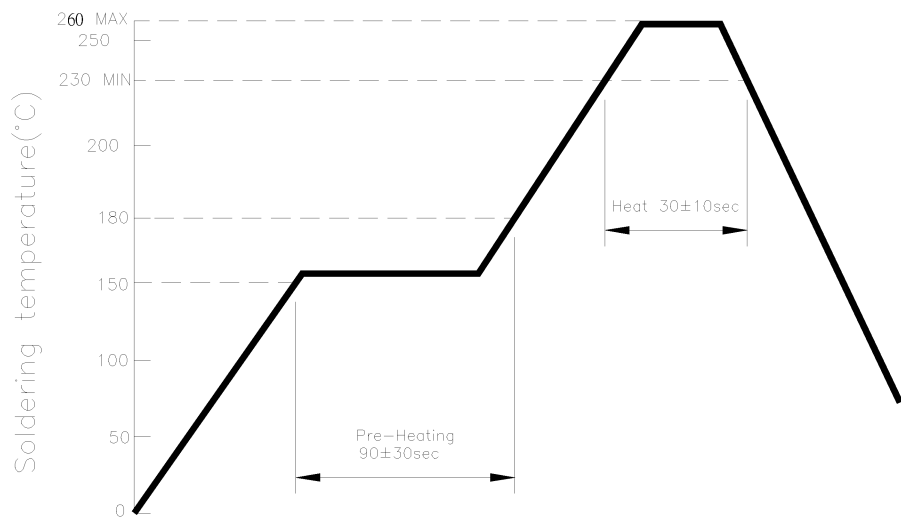


Fig.3-2 Temperature Profile of Reflow Soldering